

4. A die bonding method according to claim 1, wherein the up/down movement of said needle is realized through rotation of a cam at a uniform velocity.

5. A die bonding method according to claim 1, wherein the up/down movement of said needle is realized through rotation of a cam at a variable velocity.

6. A die bonding method according to claim 1,

wherein a resin having a viscosity of from 100 to 300 PS is used as said adhesive agent, and said first velocity is lower than 40 mm/sec.

7. A die bonding method according to claim 6, wherein said second velocity has an average velocity of 100 mm/sec.

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